



ASML NXE Pellicle progress update

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2016 EUV Mask Pellicle TWG

San Jose CA

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- Introduction: a look back at 2015
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NXE pellicle development

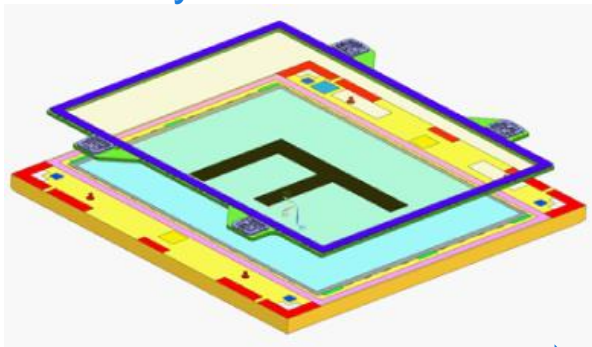
NXE pellicle: from concept to reality

February 2015

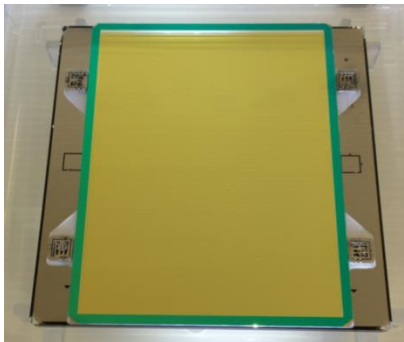
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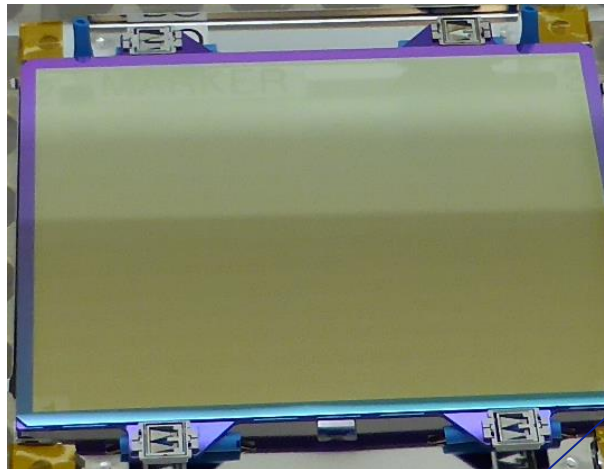
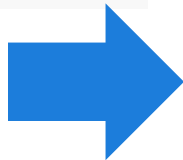
Current design



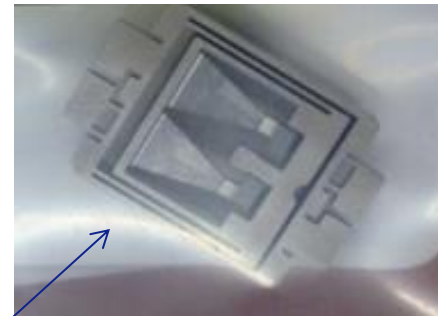
NXE pellicle concept



NXE pellicle demonstration model

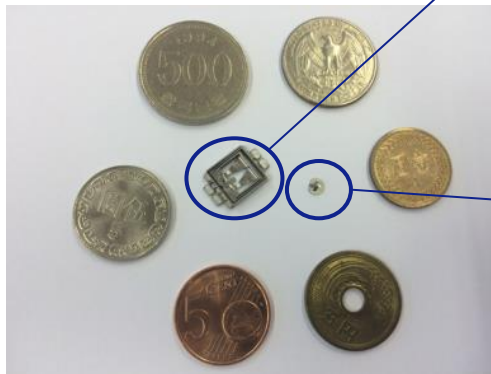


Fixtures



Studs

(interface to reticle)



NXE Pellicles are being mounted on reticles and exposed

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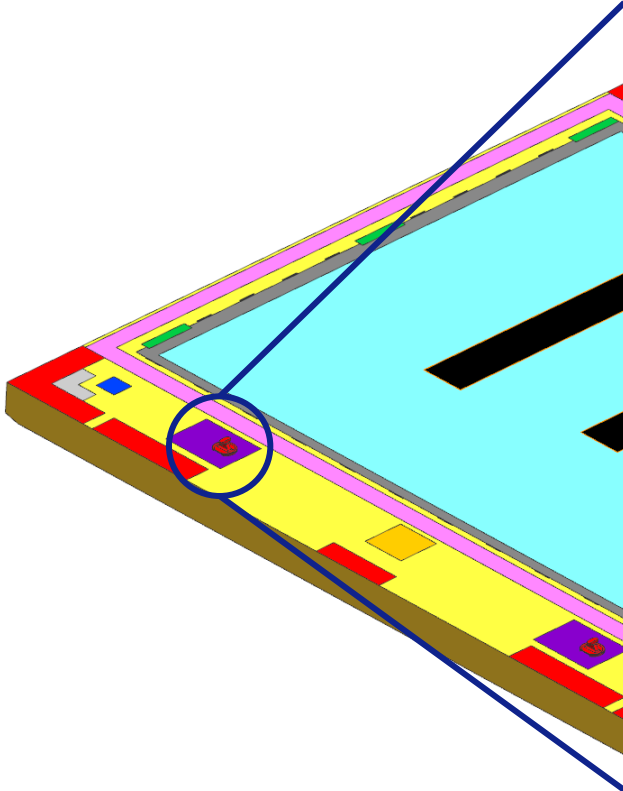
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NXE pellicle update

NXE pellicle: from concept to reality

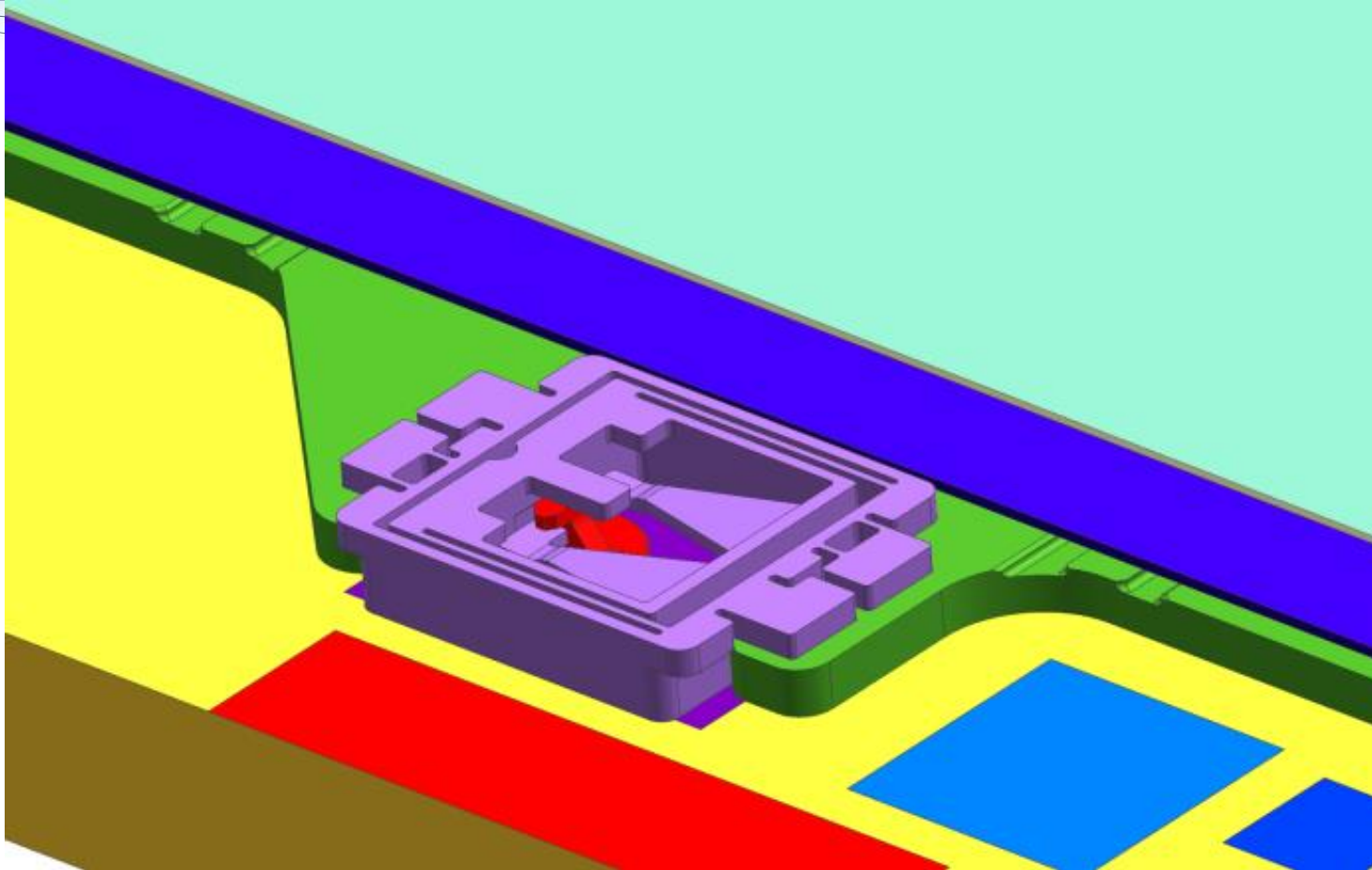
Mount-demount principle without any sliding motion



NXE pellicle: from concept to reality

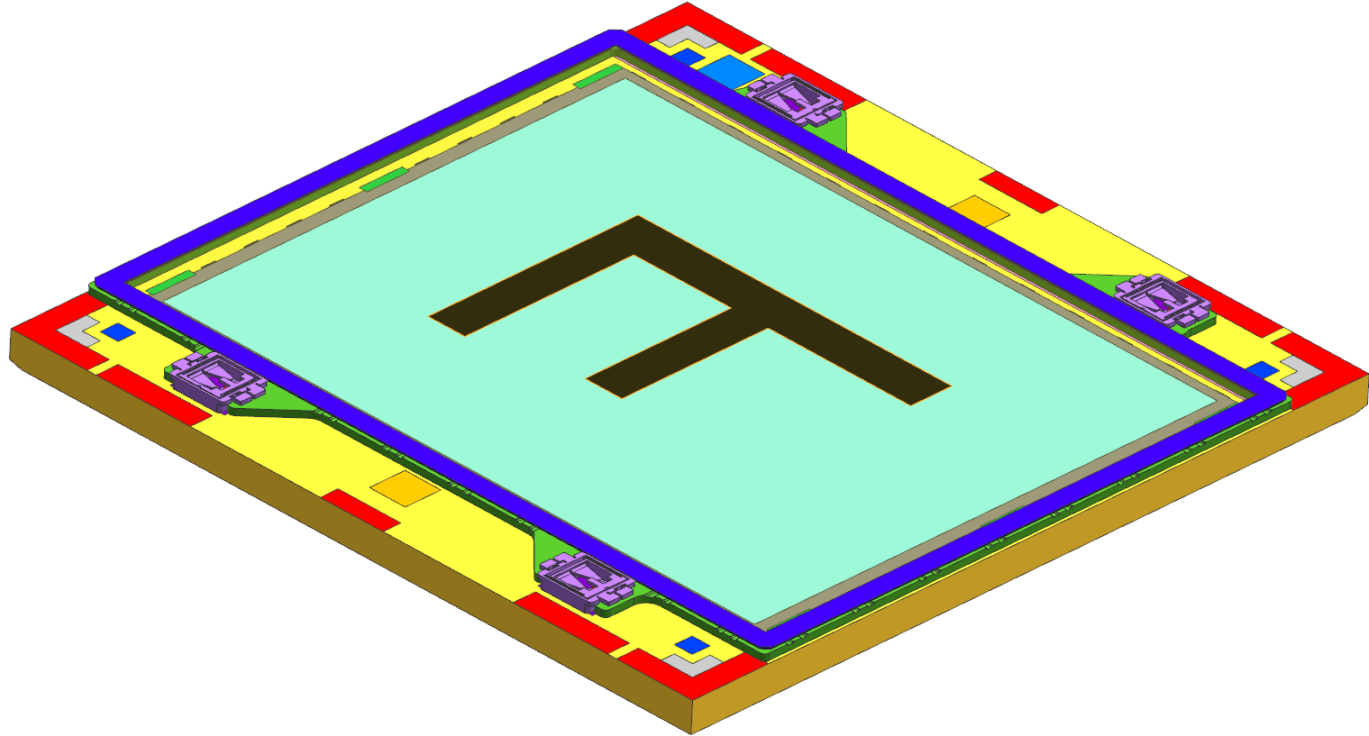
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NXE pellicle: from concept to reality

Close proximity mount to limit reticle deformation and allow venting



NXE pellicle tooling to support pellicle use in mask shops available 2nd half of 2016

Three tools developed:

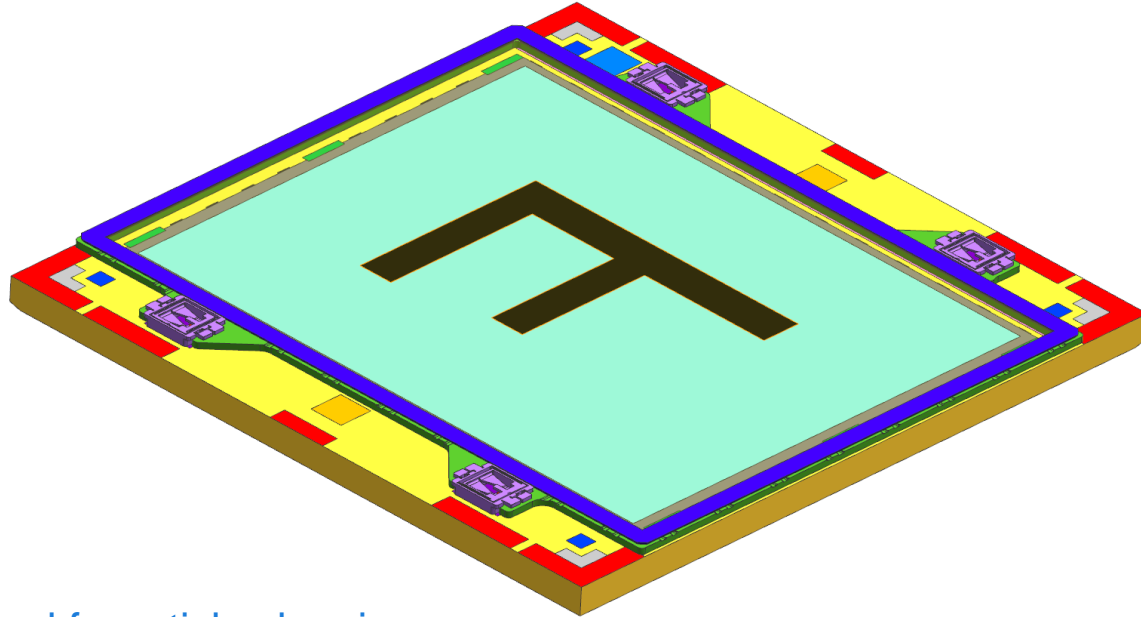
1. Mount studs
2. Mount, demount remount pellicle (→)
3. Remove studs

Key features:

- Optimized design for cleanliness
- No manual reticle or pellicle handling
- Mount-demount principle without any sliding motion.

NXE pellicle: from concept to reality

Removeable NXE pellicle allows for patterned mask inspection



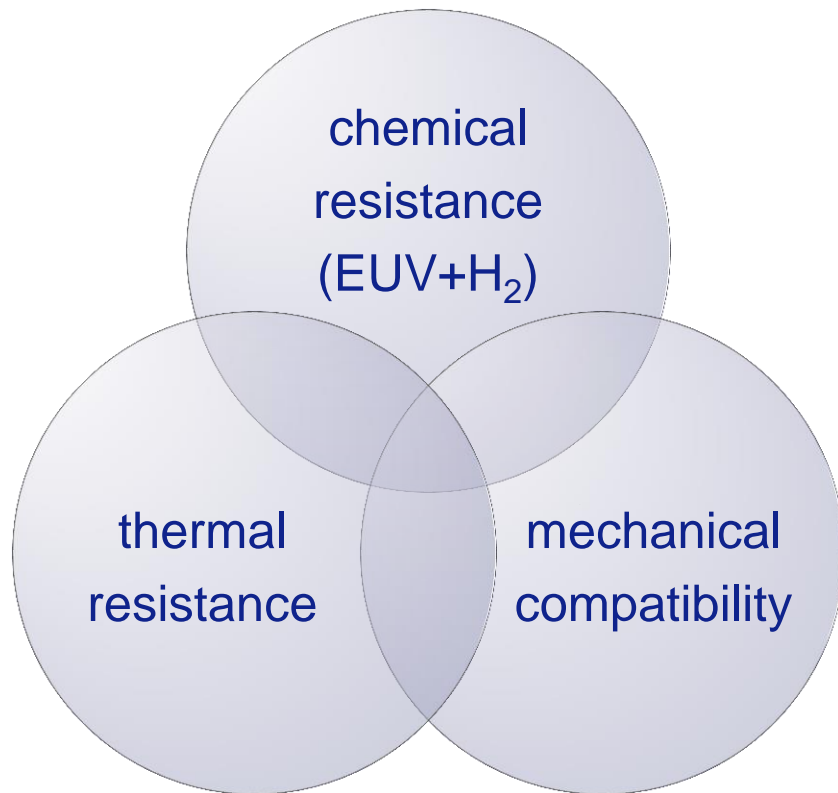
- Studs can be removed for reticle cleaning
- Alternatively, localized reticle cleaning could be done with the studs on

Pellicle Film Development

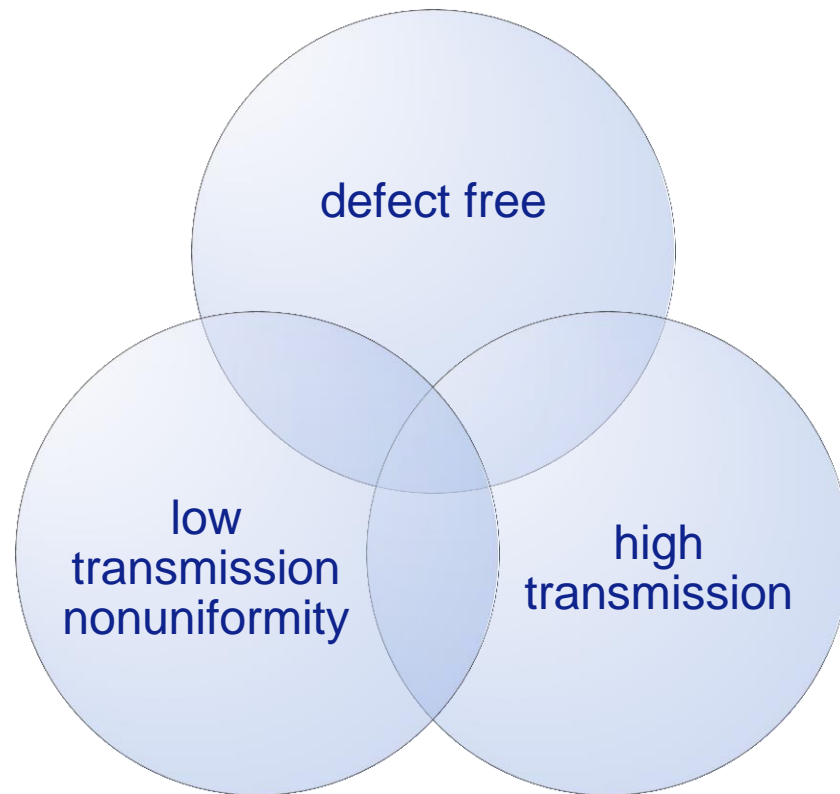
Pellicle film must simultaneously fulfill all key requirements

Polycrystalline silicon based films meet the key requirements

Pellicle robustness



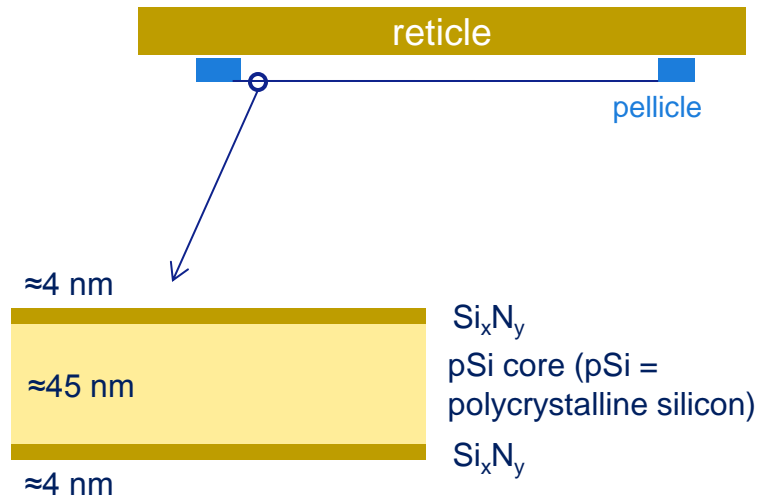
Scanner (imaging) performance



Pellicle film: Performance roadmap

Continuous improvement plan for pellicle films

| Pellicle film generations | Product Phase | Target specifications | | |
|---------------------------|---------------|---------------------------|--|------------------|
| | | Transmission ¹ | Transmission non-uniformity ² | Power capability |
| | Prototype | >80% | 1% | >40W |
| | Pilot | >80% | 1% | >125W |
| | Product | 88% | 0.4% | 250W |
| | Future | ≥90% | 0.4% | >250W |



¹ Single pass transmission at 6 deg angle of incidence

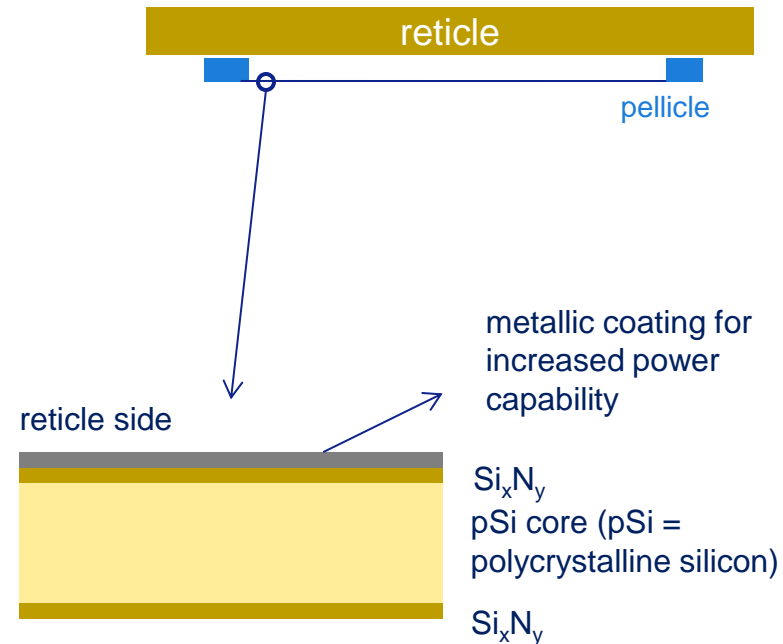
² Half range; single pass

Pellicle film: Performance roadmap

Pilot film with increased power capability

Pellicle film
generations

| Product Phase | Target specifications | | |
|---------------|---------------------------|--|------------------|
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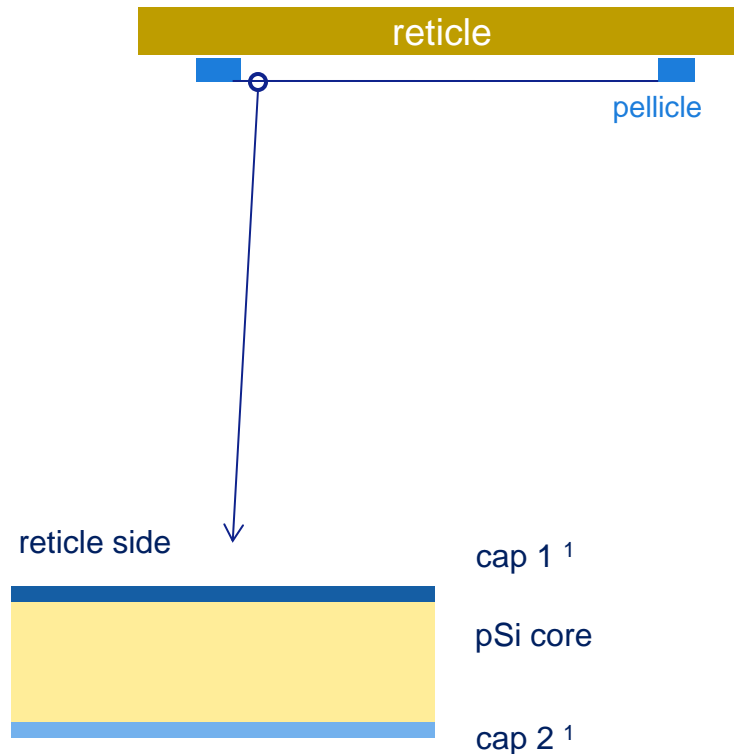


Pellicle film: Performance roadmap

Product film with new capping materials

Pellicle film
generations

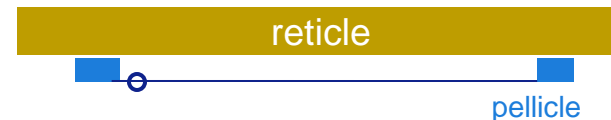
| | Product Phase | Target specifications | | |
|--|---------------|-----------------------|-----------------------------|------------------|
| | | Transmission | Transmission non-uniformity | Power capability |
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| | Pilot | >80% | 1% | >125W |
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¹ Various materials are being characterized

Pellicle film: Performance roadmap

Research activities



| | Product Phase | Target specifications | | |
|---------------------------|---------------|-----------------------|-----------------------------|------------------|
| | | Transmission | Transmission non-uniformity | Power capability |
| Pellicle film generations | Prototype | >80% | 1% | >40W |
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In parallel, ASML Research investigates pellicle robustness, primarily thermal resistance based upon:

- Graphene/carbon based membranes (96% transmission achieved on carbon based films)
- New multilayer structures
- High temperature ceramics as capping and base material

NXE Scanner readiness

NXE scanner readiness for robust operation with pellicle

- Prevention
- Detection
- Recovery

Optimized scanner flow configuration

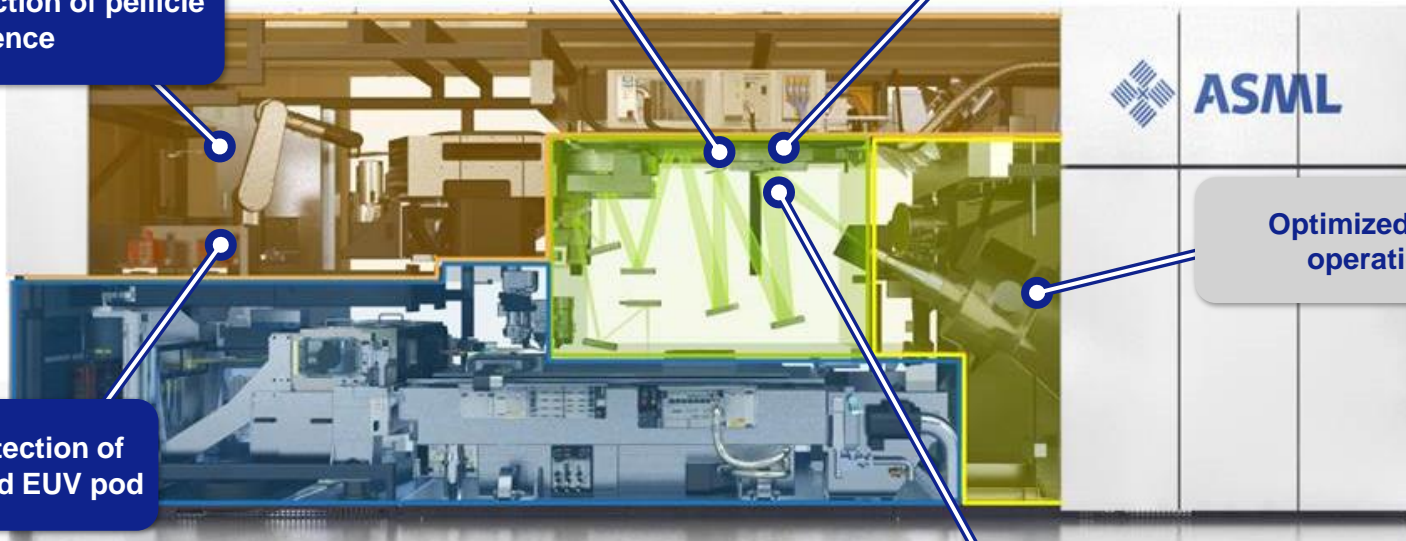
Reticle stage: detection of pellicle presence between exposures

Load lock: detection of pellicle presence

Load lock: detection of pellicle modified EUV pod

Optimized EUV source operation modes

Protocol established and tested in preparation for any pellicle failure event



200 wafers exposed using reticle with 40W pellicle

Collaborative effort between Intel and ASML

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200 wafers exposed
with NXE Pellicle



- **NO RETICLE ADDERS OBSERVED IN WAFER PRINTS**
- **Particles on pellicle do not appear to migrate to reticle surface**
- **ASML pellicle frame design is mitigating adder rate**
 - **defectivity assessment continuing**

EUV defectivity
reticle shipped

- **Global transport**
- **Multiple location handling**

Exposure testing will continue to 1000+ wafers with NXE Pellicle

Summary

- NXE Pellicle has moved from concept to realization phase
- Mask shop tooling to support NXE Pellicle in mask shop flow is defined. Development is driven to achieve defect free mounting and demounting
- Pellicle film roadmap established with plan to support higher EUV powers and improve imaging performance
- NXE scanners can be adapted with multiple new features for robust NXE Pellicle operation.

The image features the ASML logo in a bold, dark blue, sans-serif font. The logo is positioned on the left side of the frame. The background is a light blue gradient with abstract, flowing white lines that sweep across the lower half of the image, creating a sense of motion and modernity.

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